

**Basic information****2013/2905(DEA)**

DEA - Delegated acts procedure

Exemption for lead in solders on printed circuit boards, termination coatings of electrical and electronic components and coatings of printed circuit boards, solders for connecting wires and cables, solders connecting transducers and sensors that are used durably at a temperature below -20°C

Supplementing [2008/0240\(COD\)](#)**Subject**

3.40.06 Electronics, electrotechnical industries, ICT, robotics  
3.70.13 Dangerous substances, toxic and radioactive wastes (storage, transport)

Procedure completed - delegated act enters into force

**Technical information****Procedure reference**

2013/2905(DEA)

**Procedure type**

DEA - Delegated acts procedure

**Procedure subtype**

Examination of delegated act

Supplementing [2008/0240\(COD\)](#)**Stage reached in procedure**

Procedure completed - delegated act enters into force

**Committee dossier**

ENVI/7/14364